



Material Content Data Sheet



Sales Product Name		BSC0501NSI		Issued		20. July 2018		
MA#		MA001300788						
Package		PG-TDSON-8-6		Weight*		115.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.393	0.34	0.34	3395	3395
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		425	
	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	copper	7440-50-8	49.082	42.45	42.50	424481	425034
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	182	182
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		718	
	plastics	epoxy resin	-	5.894	5.10		50978	
	inorganic material	silicondioxide	60676-86-0	35.533	30.73	35.90	307303	358999
leadfinish	non noble metal	tin	7440-31-5	1.452	1.26	1.26	12555	12555
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1432	1432
solder	noble metal	silver	7440-22-4	0.016	0.01		134	
	non noble metal	tin	7440-31-5	0.012	0.01		107	
	non noble metal	lead	7439-92-1	0.592	0.51	0.53	5123	5364
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		193	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	copper	7440-50-8	22.292	19.28	19.31	192788	193039
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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